

# **VPX Conduction Cooled SSD Module with PCIe Interface**

RRT-3UVPX-PCIe-C

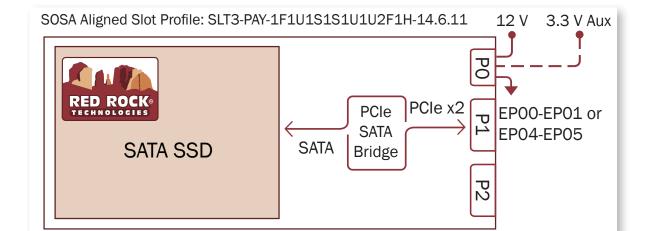
THE 3U VPX CONDUCTION COOLED SSD MODULE WITH PCIE INTERFACE to VPX backplane adds SSD to a VPX system using one 3U VPX slot with COTS 2.5" SATA Solid State Drives (SSDs) providing capacities up to 20TB and transfer rates of up to 600MB/S. Options for FIPS140-2, FIPS197, TCG Opal, and military erase.

- Capacities up to 20TB
- 600MB/S transfer rates
- OpenVPX Thin Pipe (TP) PCIe x2 interface
- VITA 65 Slot Profiles:
  - SLT3-PAY-1F1U1S1S1U1U2F1H-14.6.11
    - VPX P1 EP00-EP01 OR
    - VPX P1 EP04-EP05
  - SLT3-PER-1F-14.3.2
- VITA 46, 47, 48, 65
- Boot and/or storage disk
- Conduction cooled
- COTS 2.5" SATA SSDs
- SATA3 (SATA600) Interface to SSD
- Military erase options, FIPS140-2, FIPS197, TCG Opal options
- IDE or AHCI Mode
- Desktop version available to connect drive module to PC
- VxWorks, Linux, Windows Support



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### **Ordering Information**

# 3U VPX Conduction Cooled SSD Module with PCIe Interface

RRT-3UVPX-PCIe-C- P1EP00EP01 20TB -**MLC** 

### Requirements

**VPX Interface** 

P1EP00EP01 Payload Slot EP00-EP01 (SOSA Aligned) P1EP04EP05 Payload Slot EP04-EP05 (SOSA Aligned)

Peripheral Slot PER

#### NAND Flash Type

**HDD** Hard Disk Drive TLC 3D NAND MLC Multi Level Cell SLC Single Level Cell

#### Capacity

1TB - 5TB For HDD 120GB - 8TB For TLC 60GB - 20TB For MLC 7GB - 240GB For SLC

### Options May be left blank

#### **Conformal Coating**

UR Polyurethane AR Acrylic

#### **Extended Temperature Range**

-40°C to 85°C Χ

#### Security

Fast Erase FΕ

SE1 NSA/CSS Manual 9-12 Erase

SE2 RCC-TG IRIG 106-107 Chapter 10 Erase

TCG OPAL Compliant SSD **OPAL** FIPS140-2 FIPS 140-2 Compliant SSD FIPS197 FIPS 197 Compliant SSD

### **ORDER EXAMPLES**

RRT-3UVPX-PCIe-A100-P1EP00EP01-MLC-20TB-UR-X-SE1 RRT-3UVPX-PCIe-A080-PER-SLC-240GB RRT-3UVPX-PCIe-A100-P1EP00EP01-TLC-8TB RRT-3UVPX-PCIe-A100-P1EP04EP05-HDD-1TB-FIPS140-2



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## **Product Specifications**

#### 3U VPX CONDUCTION COOLED SSD MODULE WITH PCIE INTERFACE

PERFORMANCE					
NAND FLASH TYPE	HDD	SSD: TLC	SSD: MLC	SSD: MLC-X	SSD: SLC
CAPACITIES <sup>1</sup>	Up to 5TB	Up to 8TB	Up to 20TB		Up to 240GB
INTERFACE <sup>2</sup>	PCle Gen 2 x 2	,		,	
THROUGHPUT - SUSTAINED	130 MB/S	400 MB/S		,	
RELIABILITY					
MTBF-DRIVE	500,000 hours	1 million hours	2 million hours		3 million hours
MTBF-VPX BOARD <sup>3</sup>	3 million hours				
DATA RETENTION	Not applicable	1 year			10 years
ENDURANCE (100GB) TOTAL BYTES WRITTEN	Not applicable	70 TBW			350 TBW
CFAST CONNECTOR MATING CYCLES	10,000 mating cycles				
POWER					
VOLTAGE-PAYLOAD SLOT	+12V, +3.3V Aux				
VOLTAGE-PERIPHERAL SLOT	+5V +/- 5%				
WATTS (IDLE)	1 W	1.2 W	3.5 W		1 W
WATTS (ACTIVE)	2.5 W	4 W	10 W		2.5 W
ENVIRONMENTAL					
OPERATING TEMP., VITA 47 CLASS	5°C to 55°C	0°C to 60°C, CC1	0°C to 70°C, CC1	See MLC	0°C to 70°C, CC1
EXTENDED OPERATING TEMP., VITA 47 CLASS <sup>4</sup>	Not available See MLC-X		-40°C to 85°C, CC4		
STORAGE TEMP.	-40°C to 70°C	C to 70°C   -40°C to 85°C			
ALTITUDE	10,000 ft. (3,000 meters)			80,000 ft. (24,000 meters)	
RELATIVE HUMIDITY	5% to 95% non-condensing				
SHOCK, VITA 47 CLASS⁵	20g, 11 millisecond terminal sawtooth pulse, OS1			40g, 11 millisecond terminal sawtooth pulse, OS2	
VIBRATION, VITA 47 CLASS <sup>6</sup>	0.04 g2/Hz, 5 Hz to 100 Hz, V1			0.1 g2/Hz, 100 Hz to 1000 Hz, V3	
PHYSICAL					
FORM FACTOR	3U VPX				
WEIGHT	10 oz. max				
PITCH	0.8"				
NOTES					

- (1) Larger capacities available as new COTS 2.5" drives released
- (2) Interface connected via compatible slot profile SLT3-PAY-1F1U1S1S1U1U2F1H-146.11 or SLT3-PER-1F-14.3.2
- (3) Telcordia SR-322, Issue 3, operating temp (40C), electrical stress (50%), environmental factor (1.0)
- (4) Thermal qualification per MIL-STD-810, Method 501, Procedure II, and MIL-STD-810, Method 502, Procedure II
- (5) Shock qualification per MIL-STD-810F, Method 516, Procedure I
- (6) Vibration qualification per MIL-STD-810F, Method 514, Procedure I



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